

METHOD OF MANUFACTURING PRINTED CIRCUIT BOARD

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Abstract of JP5160557

PURPOSE: To form a solder resist pattern with high precision in an excellent processing capacity by a method wherein the process between the silk screen printing process and the liquid photosolder resist process is used.

CONSTITUTION: The whole surface of a printed board with a copper foil pattern formed by etching step thereon is printed with the first solder resist ink and then preset by a conveyor ultraviolet ray setting furnace, model HMW-713, at a light quantity of 600mJ/cm² to form solder resist into a film. Next, the whole surface is pattern-printed with the second solder resist ink to be set by the setting furnace at the light quantity of 500mJ/cm². Next, the printed board wherein a patterned resist film is formed on the solder resist film is dipped in 3Wt% of NaOH solution for three minutes so as to develop and remove the solder resist film on the part where no patterned resist exists at all. Finally, the second solder resist ink is exposed by the setting furnace at a light quantity of 1000mJ/cm².

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